

Silicon P Channel MOS Type (U-MOSII)/Silicon Epitaxial Schottky Planar Diode

# SSM5G01TU

DC-DC Converter for DSCs and Camcorders

- Co-packaged Pch MOSFET and Schottky Diode.
- Low R<sub>DS</sub> (ON) and Low V<sub>F</sub>

## Maximum Ratings (Ta = 25°C)

Characteristics	Symbol	Rating	Unit
Drain-Source voltage	V <sub>DS</sub>	-30	V
Gate-Source voltage	V <sub>GSS</sub>	±20	V
Drain current	DC	I <sub>D</sub>	-1.0
	Pulse	I <sub>DP</sub> (Note 2)	-2.0
Channel temperature	P <sub>D</sub> (Note 1)		0.5
		t = 10s	0.8
Channel temperature	T <sub>ch</sub>	150	°C

## Maximum Ratings (Ta = 25°C) SCHOTTKY DIODE

Characteristics	Symbol	Rating	Unit
Maximum (peak) reverse voltage	V <sub>RM</sub>	25	V
Reverse voltage	V <sub>R</sub>	20	V
Average forward current	I <sub>O</sub>	0.5	A
Peak one cycle surge forward current (non-repetitive)	I <sub>FSM</sub>	2 (50 Hz)	A
Junction temperature	T <sub>j</sub>	125	°C

## Maximum Ratings (Ta = 25°C) MOSFET, DIODE COMMON

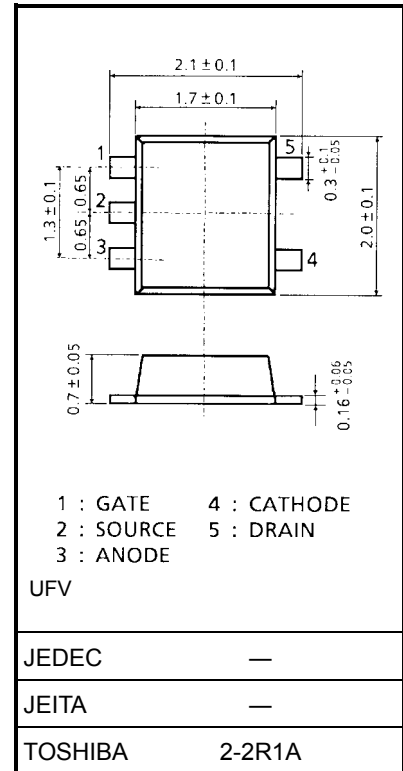
Characteristics	Symbol	Rating	Unit
Storage temperature	T <sub>stg</sub>	-55~125	°C
Operating temperature	T <sub>opr</sub> (Note 3)	-40~100	°C

Note 1: Mounted on FR4 board  
(25.4 mm × 25.4 mm × 1.6 t, Cu pad: 645 mm<sup>2</sup>)

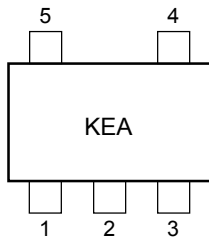
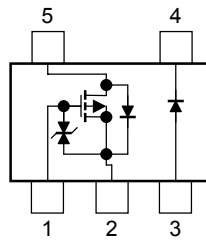
Note 2: The pulse width limited by max channel temperature.

Note 3: Operating temperature limited by max channel temperature and max junction temperature.

Unit: mm



Weight: 7 mg (typ.)

**Marking****Equivalent Circuit****Handling Precaution**

When handling individual devices (which are not yet mounting on a circuit board), be sure that the environment is protected against electrostatic electricity. Operators should wear anti-static clothing, and containers and other objects that come into direct contact with devices should be made of anti-static materials.

The Channel-to-Ambient thermal resistance  $R_{th(ch-a)}$  and the drain power dissipation  $P_D$  vary according to the board material, board area, board thickness and pad area are also affected by the environment in which the product is used. When using this device, please take heat dissipation fully into account.

## MOSFET

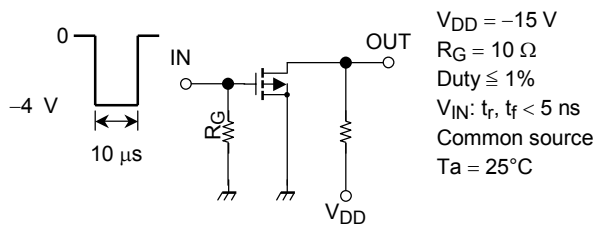
### Electrical Characteristics (Ta = 25°C)

Characteristic		Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current		$I_{GSS}$	$V_{GS} = \pm 16\text{ V}, V_{DS} = 0$	—	—	$\pm 1$	$\mu\text{A}$
Drain-Source breakdown voltage		$V_{(BR)DSS}$	$I_D = -1\text{ mA}, V_{GS} = 0$	-30	—	—	V
		$V_{(BR)DSX}$	$I_D = -1\text{ mA}, V_{GS} = 20\text{ V}$	-15	—	—	
Drain Cut-off current		$I_{DSS}$	$V_{DS} = -30\text{ V}, V_{GS} = 0$	—	—	-1	$\mu\text{A}$
Gate threshold voltage		$V_{th}$	$V_{DS} = -5\text{ V}, I_D = -0.1\text{ mA}$	-0.8	—	-1.8	V
Forward transfer admittance		$ Y_{fs} $	$V_{DS} = -5\text{ V}, I_D = -0.5\text{ A}$ (Note 4)	0.5	1.0	—	S
Drain-Source ON resistance		$R_{DS(ON)}$	$I_D = -0.5\text{ A}, V_{GS} = -10\text{ V}$ (Note 4)	—	0.3	0.4	$\Omega$
			$I_D = -0.5\text{ A}, V_{GS} = -4\text{ V}$ (Note 4)	—	0.6	0.8	
Input capacitance		$C_{iss}$	$V_{DS} = -15\text{ V}, V_{GS} = 0, f = 1\text{ MHz}$	—	86	—	pF
Reverse transfer capacitance		$C_{rss}$	$V_{DS} = -15\text{ V}, V_{GS} = 0, f = 1\text{ MHz}$	—	14	—	pF
Output capacitance		$C_{oss}$	$V_{DS} = -15\text{ V}, V_{GS} = 0, f = 1\text{ MHz}$	—	25	—	pF
Switching time	Turn-on time	$t_{on}$	$V_{DD} = -15\text{ V}, I_D = -0.5\text{ A}$	—	14	—	ns
	Turn-off time	$t_{off}$	$V_{GS} = 0 \sim -4\text{ V}, R_G = 10\ \Omega$	—	8.5	—	

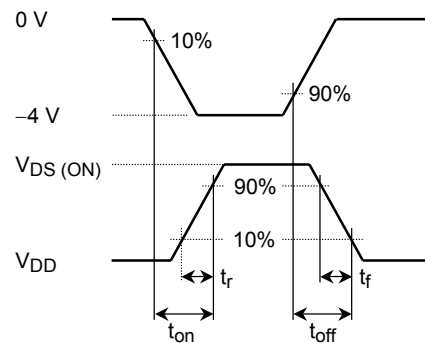
Note 4: Pulse measurement

### Switching Time Test Circuit

#### (a) Test circuit



#### (b) $V_{IN}$



#### (c) $V_{OUT}$

### Precaution

$V_{th}$  can be expressed as voltage between gate and source when low operating current value is  $I_D = -100\ \mu\text{A}$  for this product. For normal switching operation,  $V_{GS(ON)}$  requires higher voltage than  $V_{th}$  and  $V_{GS(OFF)}$  requires lower voltage than  $V_{th}$ .

(Relationship can be established as follows:  $V_{GS(OFF)} < V_{th} < V_{GS(ON)}$ )

Please take this into consideration for using the device.

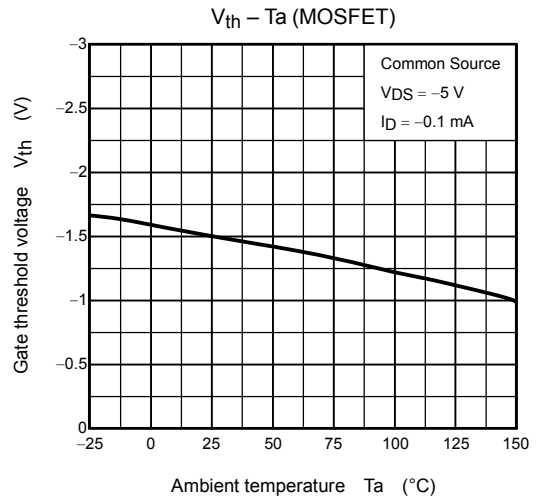
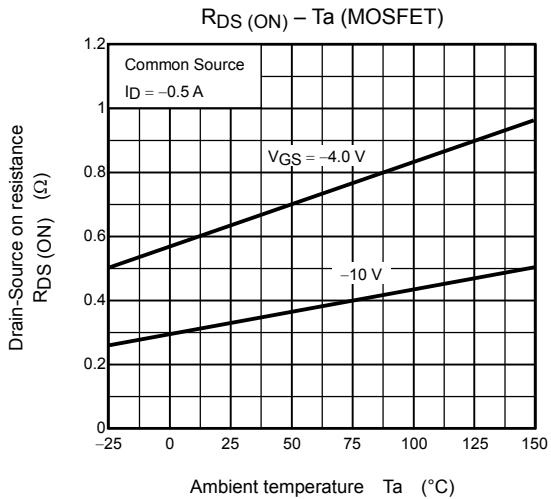
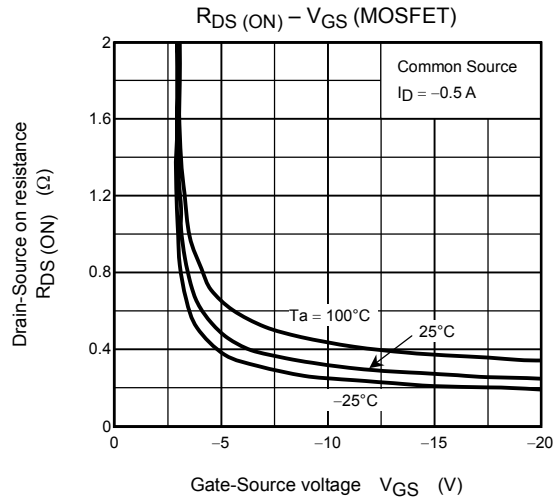
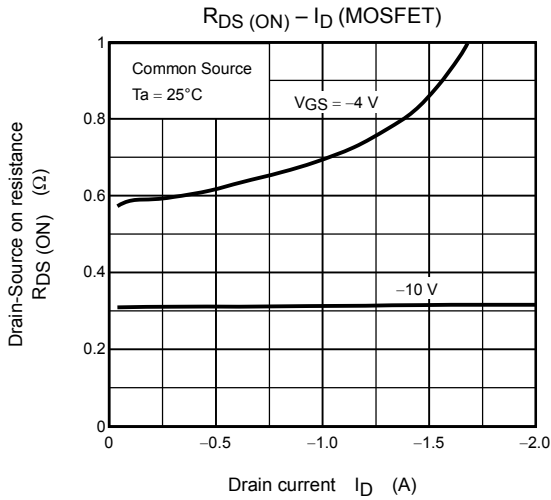
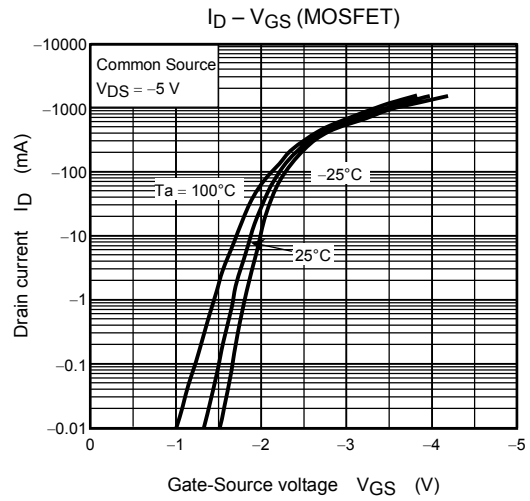
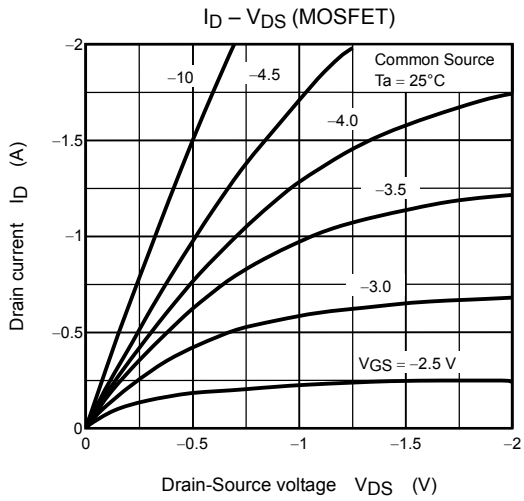
$V_{GS}$  recommended voltage of  $-2.5\text{ V}$  or higher to turn on this product.

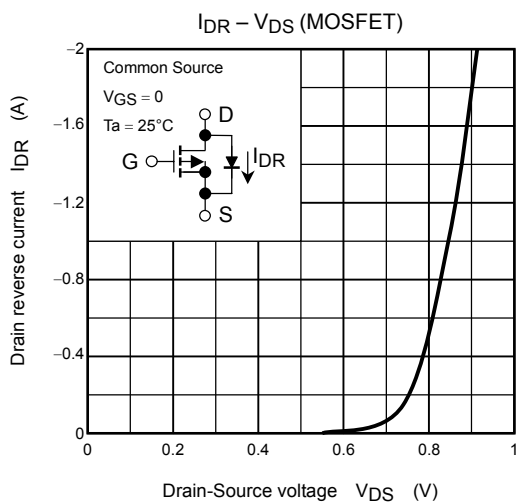
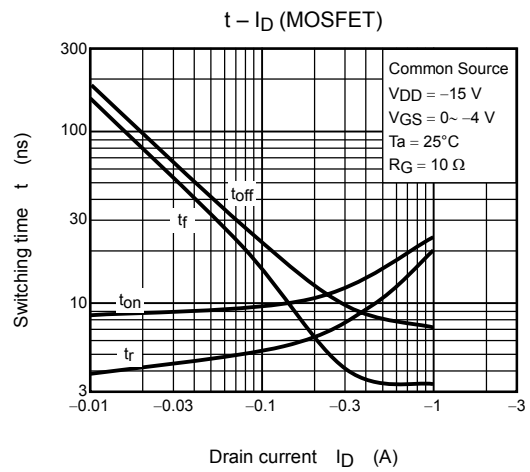
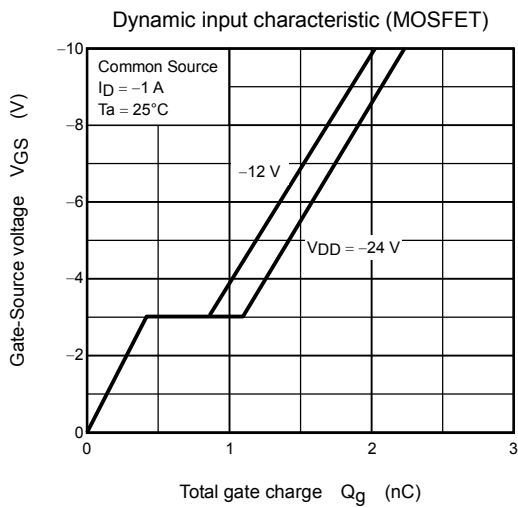
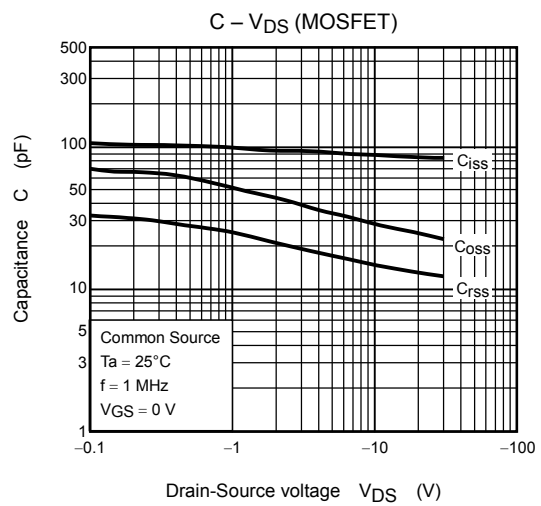
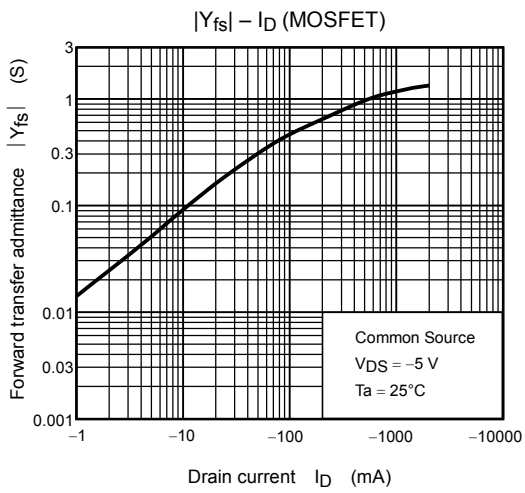
**Schottky Diode****Electrical Characteristics (Ta = 25°C)**

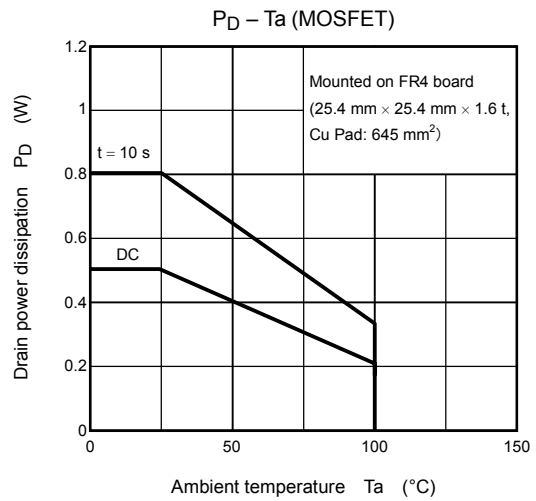
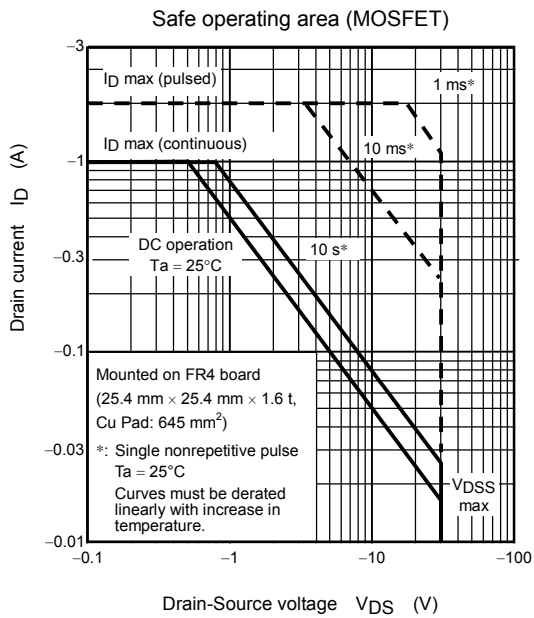
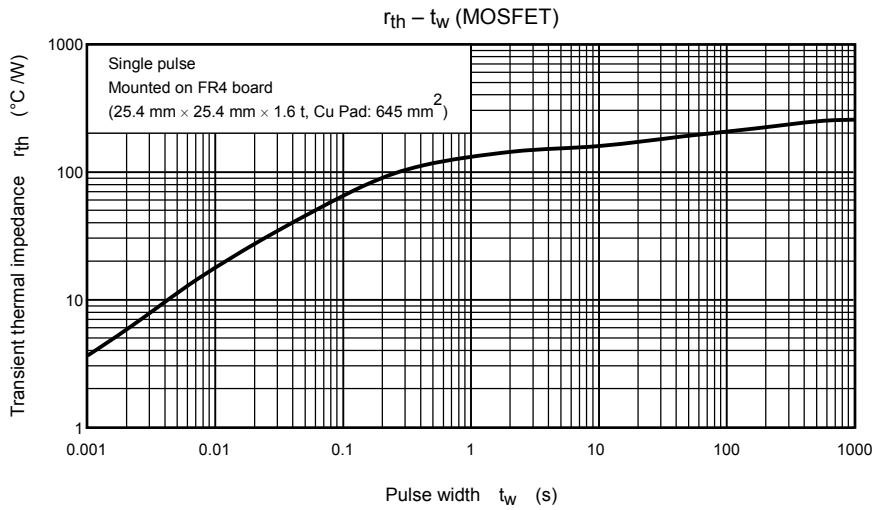
Characteristic	Symbol	Test Condition	Min	Typ.	Max	Unit
Forward voltage	$V_F(1)$	$I_F = 0.3 \text{ A}$	—	0.38	0.45	V
	$V_F(2)$	$I_F = 0.5 \text{ A}$	—	0.43	—	V
Reverse current	$I_R$	$V_R = 20 \text{ V}$	—	—	50	$\mu\text{A}$
Total capacitance	$C_T$	$V_R = 0 \text{ V}, f = 1 \text{ MHz}$	—	46	—	pF

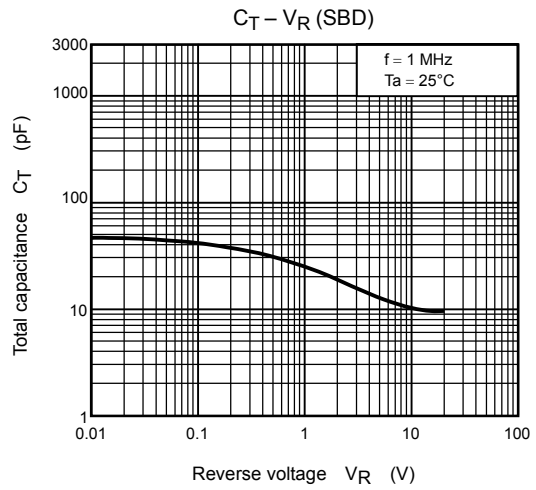
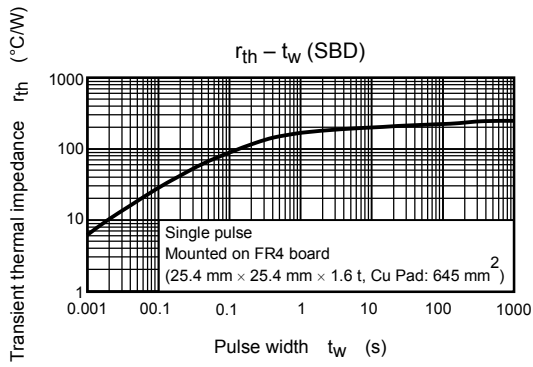
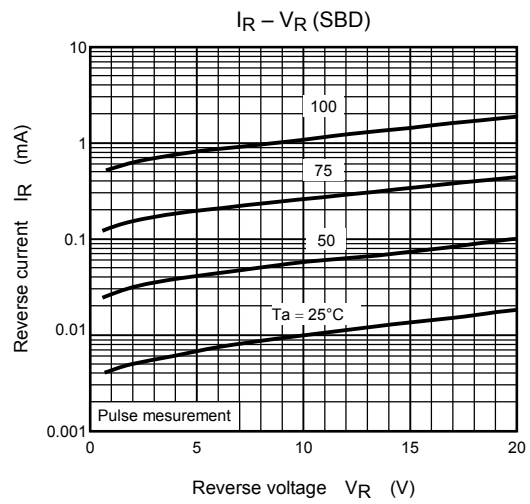
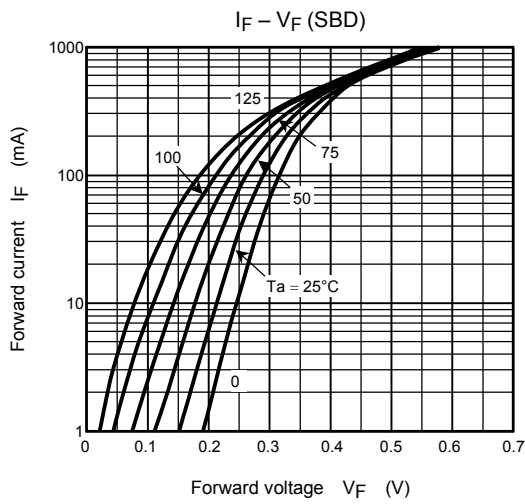
**Precaution**

The schottky barrier diode of this product are having large-reverse-current-leakage characteristic compare to the other switching diodes. This current leakage and not proper operating temperature or voltage may cause thermal runaway. Please take forward and reverse loss into consideration when you design.











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